## 20W, 3GHz General Purpose RF LDMOS FETs

### Description

The MM2002A is a 20-watt, highly rugged, unmatched LDMOS FET, designed for wideband commercial and industrial applications at frequencies up to 3 GHz. It can be used in Class AB/B and Class C for all typical modulation formats. It can support CW, pulsed CW either saturated or linear operation.

• Typical Performance (On Innogration fixture with device soldered):

V <sub>DD</sub> = 28 Volts, I <sub>DQ</sub> =	= 50 mA,	CW.
---	----------	-----

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
2800	45.63	36.5	49.6	10.86	46.42	43.9	51.7
2850	45.02	31.8	51.5	11.65	45.83	38.3	53.6
2900	44.05	25.4	49.4	11.6	44.89	30.8	51.8

## Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

## **Suitable Applications**

- General purpose power amplifier
- L, S band power amplifier

### Table 1. Maximum Ratings

Rating	Symbol	Value	Unit			
DrainSource Voltage	V <sub>DSS</sub>	+65	Vdc			
GateSource Voltage	V <sub>GS</sub>	-10 to +10	Vdc			
Operating Voltage	V <sub>DD</sub>	+32	Vdc			
Storage Temperature Range	Tstg	-65 to +150	°C			
Case Operating Temperature	Tc	+150	°C			
Operating Junction Temperature	TJ	+225	°C			
Fable 2. Thermal Characteristics						
Characteristic	Symbol	Value	Unit			

Onaracionstic	Gymbol	Value					
Thermal Resistance, Junction to Case	Rejc	1.6	°C/W				
$T_c$ = 85°C, $T_J$ =200°C, DC test	RejC	1.0	C/VV				
Table 3 ESD Protection Characteristics							

#### Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

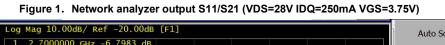


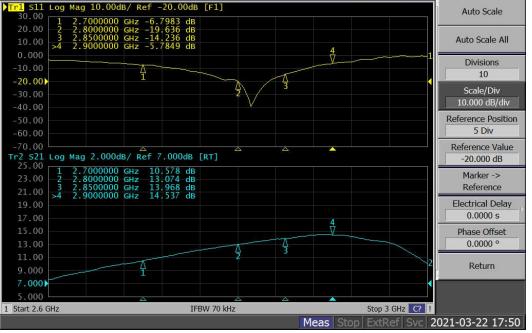
Document Number: MM2002A Product Datasheet V1.0

#### Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OC Characteristics						
Drain-Source Voltage	N	65	70		V	
V <sub>GS</sub> =0, I <sub>DS</sub> =500uA	V <sub>(BR)DSS</sub>	60	70		v	
Zero Gate Voltage Drain Leakage Current				1		
(V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0 V)	DSS				μA	
Zero Gate Voltage Drain Leakage Current				1		
(V <sub>DS</sub> = 28 V, V <sub>GS</sub> = 0 V)	DSS			1	μΑ	
GateSource Leakage Current				1	•	
$(V_{GS} = 9 V, V_{DS} = 0 V)$	I <sub>GSS</sub>				μA	
Gate Threshold Voltage	M (m)		1.98		V	
$(V_{DS} = 28V, I_{D} = 600 \ \mu A)$	$V_{GS}(th)$				v	
Gate Quiescent Voltage	N		2.53		V	
(V_{DD} = 28 V, I_D = 50 mA, Measured in Functional Test)	V <sub>GS(Q)</sub>		2.55		V	
Common Source Input Capacitance			23.5		۳Ľ	
(V <sub>GS</sub> = 0V, V <sub>DS</sub> =28 V, f = 1 MHz)	C <sub>ISS</sub>		23.5		pF	
Common Source Output Capacitance			0.7			
(V <sub>GS</sub> = 0V, V <sub>DS</sub> =28 V, f = 1 MHz)	Coss		9.7		pF	
Common Source Feedback Capacitance						
(V <sub>GS</sub> = 0V, V <sub>DS</sub> =28 V, f = 1 MHz)	C <sub>RSS</sub>		0.7		pF	
.oad Mismatch (In Innogration Test Fixture, 50 ohm system): $$ $$ $$	$V_{\text{DD}} = 28 \text{ Vdc}, \text{ I}_{\text{DQ}} = 3$	50 mA, f = 290	0 MHz			
VSWR 10:1 at 20W pulse CW Output Power	No Device D	egradation				

## **TYPICAL CHARACTERISTICS**





Document Number: MM2002A Product Datasheet V1.0

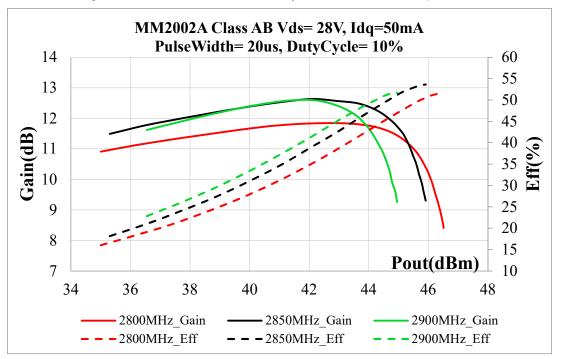
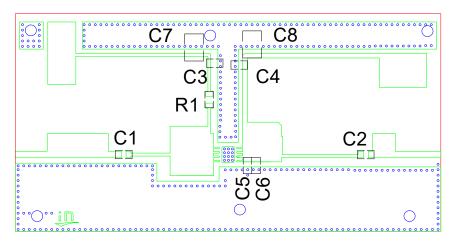


Figure 2. Power Gain and Drain Efficiency as Function of Pulse Output Power

Figure 3. Test Circuit Component Layout (PCB: 20 Mils, RO4350B)

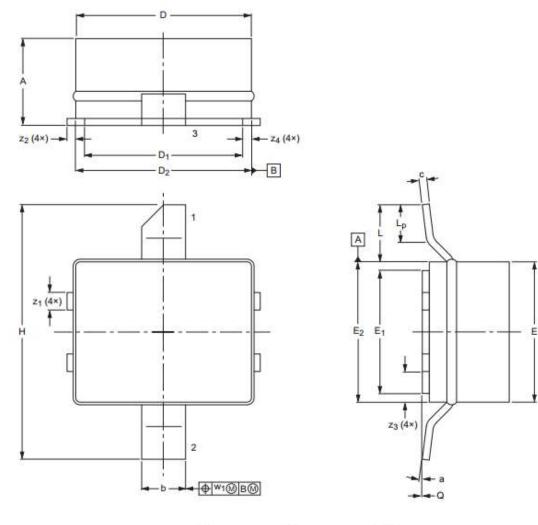




Designator	Comment	Footprint	Quantity
C1	3.9pF	0603	1
C2, C3, C4	8.2pF	0603	3
C5	0.5pF	0603	1
C6	0.3pF	0603	1
C7, C8	10uF/100V	1210	2
R1	10ohm	0603	1

## Package Outline

Earless Flanged ceramic package; 2 leads(1-Drain,2-Gate,3-Source)



0 2.5 5 mm scale

UNIT	A	b	с	D	D1	Е	E1	E <sub>2</sub>	н	L	L <sub>P</sub>	Q	W1	<b>Z</b> 1	<b>Z</b> 2	<b>Z</b> 3	<b>Z</b> 4	α
	2.34	1.35	0.23	5.16	4.65	4.14	3.63	4.14	7.49	2.03	1.02	0.1	0.05	0.58	0.25	0.97	0.51	7°
mm	2.13	1.19	0.18	5.00	4.50	3.99	3.48	3.99	7.24	1.27	0.51	0.0	0.25	0.43	0.18	0.81	0.00	0°

OUTLINE		REFERENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ICCCL DATE
PKG-MM					18/6/2014

## **Revision history**

#### Table 5. Document revision history

Revision	Datasheet Status
Rev 1.0	Product Datasheet

Application data based on LSM-21-07

### Disclaimers

Specifications are subject to change without notice. Innogration believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Innogration for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Innogration . Innogration makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Innogration in large quantities and are provided for information purposes only. These values can and do vary in different applications and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Innogration products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Innogration product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility. For any concerns or questions related to terms or conditions, pls check with Innogration and authorized distributors Copyright © by Innogration (Suzhou) Co.,Ltd.